

TRADEMARK ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT		
NATURE OF CONVEYANCE:	Intellectual Property Security Agreement		
CONVEYING PARTY DATA			
Name	Formerly	Execution Date	Entity Type
Infinera Corporation		06/21/2005	CORPORATION: DELAWARE
RECEIVING PARTY DATA			
Name:	United Commercial Bank		
Street Address:	5201 Great American Parkway, Suite 300		
Internal Address:	attn.: Johnny Lee		
City:	Santa Clara		
State/Country:	CALIFORNIA		
Postal Code:	95054		
Entity Type:	Bank:		
PROPERTY NUMBERS Total: 5			
Property Type	Number	Word Mark	
Registration Number:	2924057	INFINERA	
Registration Number:	2867867	INFINERA DIGITAL OPTICAL NETWORK	
Serial Number:	78559255	IPIC	
Serial Number:	78542692	INFINERA	
Serial Number:	78455982	IQ	
CORRESPONDENCE DATA			
Fax Number:	(650)849-7400		
	<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>		
Phone:	6508435381		
Email:	dsanchezbentz@cooley.com		
Correspondent Name:	Diana Sanchez Bentz		
Address Line 1:	Cooley Godward LLP, 5 Palo Alto Square		
Address Line 2:	3000 El Camino Real		
Address Line 4:	Palo Alto, CALIFORNIA 94306		

CH \$140.00 2924057

NAME OF SUBMITTER:	Diana Sanchez Bentz
Signature:	/dsb4232/
Date:	06/27/2005
Total Attachments: 6 source=Infinera IPSA#page1.tif source=Infinera IPSA#page2.tif source=Infinera IPSA#page3.tif source=Infinera IPSA#page4.tif source=Infinera IPSA#page5.tif source=Infinera IPSA#page6.tif	

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INTELLECTUAL PROPERTY SECURITY AGREEMENT

THIS INTELLECTUAL PROPERTY SECURITY AGREEMENT is entered into as of June 21, 2005 by and between UNITED COMMERCIAL BANK ("Bank") and INFINERA CORPORATION, a Delaware corporation ("Grantor").

RECITALS

Grantor and Bank are parties to that certain Loan and Security Agreement of even date (as amended from time to time, the "Loan Agreement"). Capitalized terms used herein have the meaning assigned in the Loan Agreement.

NOW, THEREFORE, Grantor agrees as follows:

AGREEMENT

To secure performance of Grantor's obligations under the Loan Agreement, Grantor grants to Bank a security interest in all of Grantor's right, title and interest in Grantor's intellectual property (including without limitation those Copyrights, Patents and Trademarks listed on Schedules A, B and C hereto), including without limitation all proceeds thereof (such as, by way of example but not by way of limitation, license royalties and proceeds of infringement suits). This security interest is granted in conjunction with the security interest granted to Bank in the Loan Agreement.

IN WITNESS WHEREOF, the parties have caused this Intellectual Property Security Agreement to be duly executed as of the first date written above.

Address of Borrower:

INFINERA CORPORATION

1322 Bordeaux Drive
Sunnyvale, CA 94089

By: W. Zarella

Title: CFO

Attn: Bill Zerella, Chief Financial Officer

Address of Bank:

UNITED COMMERCIAL BANK

5201 Great American Parkway, Suite 300
Santa Clara, CA 95054
Attn: Johnny Lee

By: [Signature]

Title: VP 6/21/05

EXHIBIT A

Copyrights

Title	Registration Number	Registration Date
NONE		

EXHIBIT B

Patents

Title	Serial /Patent Number	Application/Issue Date
Electrical isolation of optical components in photonic integrated circuits (PICs)	6771682	August 3, 2004
Optical modulator driver circuit with low power dissipation	6707589	March 16, 2004
Oxygen-doped Al-containing current blocking layers in active semiconductor devices	6891202	May 10, 2002
Passivation of photonic integrated circuits (PICs)	11018162	December 21, 2004
Chromatic dispersion compensator (CDC) in a photonic integrated circuit (PIC) chip and method of operation	10971890	October 22, 2004
Method of reducing insertion loss in a transition region between a plurality of input or output waveguides to a free space coupler region	11018161	December 21, 2004
In-wafer testing of integrated optical components in photonic integrated circuits (PICs)	11014410	December 16, 2004
In-wafer testing of integrated optical components in photonic integrated circuits (PICs)	11014407	December 14, 2004
Monolithic transmitter/receiver photonic integrated circuit (Tx/RxPIC) transceiver chip	10999742	November 30, 2004
Method for forming and apparatus comprising optical waveguides leading to a free space coupler region	11018149	December 21, 2004
Optical waveguide device with reduced insertion loss between optical waveguides coupled to a free space region	11018630	December 21, 2004
Method and apparatus for a polarization insensitive arrayed waveguide grating (AWG)	11016241	December 17, 2004
Probe card for testing in-wafer photonic integrated circuits (PICs) and method of use	10990042	November 16, 2004
Method of calibrating a monolithic transmitter photonic integrated circuit (TxPIC) chip	10989969	November 16, 2004
Method of in-wafer testing of monolithic photonic integrated circuits (PICs) formed in a semiconductor wafer	10988067	November 12, 2004
Monitoring of a laser source with front and rear output photodetectors to determine frontal laser power and power changes over laser lifetime	10961857	October 8, 2004

Title	Serial /Patent Number	Application/Issue Date
Method and apparatus for providing an antireflection coating on the output facet of a photonic integrated circuit (PIC) chip	10987807	November 11, 2004
Transmission line with low dispersive properties and its application in equalization	10927565	August 26, 2004
Oxygen-doped Al-containing current blocking layers in active semiconductor devices in photonic integrated circuits (PICs)	10944334	September 17, 2004
Submount for a photonic integrated circuit (PIC) chip	10852988	May 25, 2004
Method of operating an array of laser sources integrated in a monolithic chip or in a photonic integrated circuit (PIC)	10917798	August 13, 2004
Contact length trimming or vernier resistor trimming of a semiconductor laser source contact to change the source applied current density and resulting operational wavelength	10915807	August 11, 2004
Optical probe and method of testing employing an interrogation beam or optical pickup	10909642	August 2, 2004
Method and apparatus of monitoring and controlling the emission wavelengths of a plurality of laser sources integrated on the same chip or in the same photonic integrated circuit (PIC)	10919161	August 16, 2004
Method of tuning integrated laser sources with integrated wavelength tuning elements on the same substrate or in a monolithic photonic integrated circuit (PIC)	10916844	August 12, 2004
Method of tuning optical components integrated on a monolithic chip	10915073	August 10, 2004
Optical communication system with multiple photonic integrated circuit (PIC) chips and an external booster optical amplifier for photonic integrated circuits (PICs)	10887630	July 9, 2004
Method of providing a low cost semiconductor transmitter photonic integrated circuit (TxPIC) chip	10887632	July 9, 2004
Oxygen-doped Al-containing current blocking layers in active semiconductor devices	10875418	June 24, 2004
Electrical isolation of optical components in photonic integrated circuits (PICs)	10807729	March 24, 2004
Transmitter and receiver photonic integrated circuit (TxPIC and RxPIC) chips utilizing compact wavelength selective combiners/decombiners	10846336	May 13, 2004
Optical transmission network with asynchronous mapping and demapping and digital wrapper frame for the same	10715947	November 18, 2003

Title	Serial /Patent Number	Application/Issue Date
Method and apparatus for deploying forward error correction in optical transmission networks and the deployment of photonic integrated circuit (PIC) chips with the same	10712732	November 12, 2003
Transmitter photonic integrated circuit (TxPIC) chips	10317935	December 11, 2002
Optical signal receiver photonic integrated circuit (RxPIC), an associated optical signal transmitter photonic integrated circuit (TxPIC) and an optical network transmission system utilizing these circuits	10267304	October 8, 2002
Electrical isolation of optical components in photonic integrated circuits (PICs)	10283476	October 30, 2002
Upgrade of optical amplifier site to a digital optical network site in an optical transmission network	10267274	October 8, 2002
Optical modulator driver circuit with low power dissipation	10317784	December 11, 2002
Insertion loss reduction, passivation and/or planarization and in-wafer testing of integrated optical components in photonic integrated circuits (PICs)	10385574	March 10, 2003
Oxygen-doped Al-containing current blocking layers in active semiconductor devices	10319962	December 16, 2002
InP-based photonic integrated circuits with Al-containing waveguide cores and InP-based array waveguide gratings (AWGs) and avalanche photodiodes (APDs) and other optical components containing an InAlGaAs waveguide core	10327362	December 20, 2002
Architecture for multi-symbol encoding and decoding	10301174	November 20, 2002
Error correction improvement for concatenated codes	10301769	November 20, 2002
Optical communication module with one or more photonic integrated circuit (PIC) chips and an external booster optical amplifier for photonic integrated circuits (PICs)	10285936	October 31, 2002
Digital optical network architecture	10267212	October 8, 2002
Transmitter photonic integrated circuits (TxPIC) and optical transport networks employing TxPICs	10267331	October 8, 2002
Transmitter photonic integrated circuit (TxPIC) chip architectures and drive systems and wavelength stabilization for TxPICs	10267330	October 8, 2002
Heat isolation and dissipation structures for optical components in photonic integrated circuits (PICs) and an optical transport network using the same	10283475	October 30, 2002
Transmitter photonic integrated circuit (TxPIC) chip with enhanced power and yield without on-chip amplification	10267346	October 8, 2002

EXHIBIT C

Trademarks

Mark	Registration / Serial Number	Registration / Application Date
INFINERA	2924057	February 1, 2005
INFINERA DIGITAL OPTICAL NETWORK	2867867	July 27, 2004
IPIC	78559255	February 2, 2005
INFINERA	78542692	January 5, 2005
IQ	78455982	July 23, 2004